FAIRCHILD SEMICONDUCTOR®

March 2009

MCT9001
Dual Phototransistor Optocouplers

Features

- Two isolated channels per package
- Two packages fit into a 16 lead DIP socket
- Underwriters Laboratory (U.L.) recognized File E90700

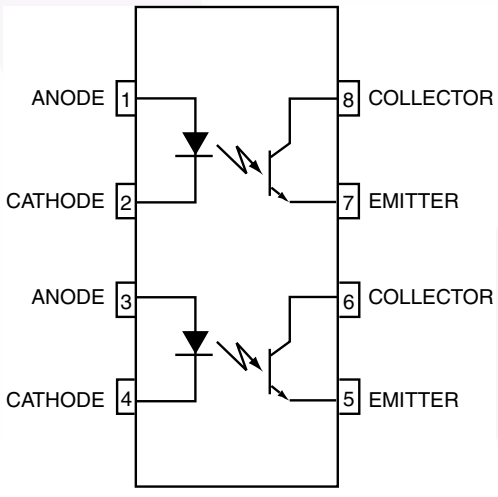
Applications

- AC line/digital logic – isolate high voltage transients
- Digital logic/digital logic – eliminate spurious grounds
- Digital logic/AC triac control – isolate high voltage transients
- Twisted pair line receiver – eliminate ground loop feedthrough
- Telephone/telegraph line receiver – isolate high voltage transients
- High frequency power supply feedback control – maintain floating grounds and transients
- Relay contact monitor – isolate floating grounds and transients
- Power supply monitor – isolate transients

Description

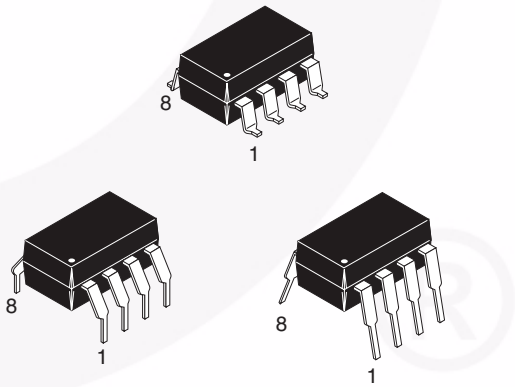
The MCT9001 Optocoupler has two channels for density applications. For four channel applications, two-packages fit into a standard 16-pin DIP socket. Each channel is an NPN silicon planar phototransistor optically coupled to a gallium arsenide infrared emitting diode.

Schematic



Equivalent Circuit

Package Outlines



Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Rating	Value	Unit
TOTAL DEVICE			
T_{STG}	Storage Temperature	-55 to +150	°C
T_{OPR}	Operating Temperature	-55 to +100	°C
T_{SOL}	Lead Solder Temperature (wave solder)	250 for 10 sec	°C
P_D	Total Device Power Dissipation @ T_A = 25°C	400	mW
	Derate above 25°C	4.83	mW/°C
EMITTER (Each channel)			
I_F	Forward Current – Continuous	60	mA
I_F(pk)	Forward Current – Peak (PW = 1µs, 300pps)	3	A
V_R	Reverse Voltage	5.0	V
P_D	LED Power Dissipation @ T_A = 25°C	100	mW
	Derate above 25°C (Total Input)	1.1	mW/°C
DETECTOR (Each channel)			
I_C	Collector Current – Continuous	30	mA
P_D	Detector Power Dissipation @ T_A = 25°C	150	mW
	Derate above 25°C	1.67	mW/°C

Electrical Characteristics (T_A = 25°C unless otherwise specified)

Individual Component Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.*	Max.	Unit
EMITTER						
V_F	Input Forward Voltage	I_F = 10mA		1.0	1.3	V
I_R	Reverse Current	V_R = 5V			10	µA
C_J	Junction Capacitance	V_F = 0 V, f = 1MHz		50		pF
DETECTOR						
BV_{CEO}	Collector-Emitter Breakdown Voltage	I_C = 0.5mA, I_F = 0	55			V
BV_{ECO}	Emitter-Collector Breakdown Voltage	I_E = 100µA, I_F = 0	7			V
I_{CEO}	Collector-Emitter Dark Current	V_{CE} = 24V, I_F = 0		5	100	nA
		V_{CE} = 24V, T_A = 85°C			50	µA
C_{CE}	Capacitance	V_{CE} = 0V, f = 1MHz		8		pF

Transfer Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.*	Max.	Units
SWITCHING TIMES (AC)						
Non-Saturated						
t_{on}	Turn-on Time	R_L = 100Ω, I_C = 2mA, V_{CC} = 10V		3		µs
t_{off}	Turn-off Time			3		µs
t_r	Rise Time			2.4		µs
t_f	Fall Time			2.4		µs
Saturated						
t_{on}	Turn-on Time	I_F = 16mA, R_L = 1.9kΩ, V_{CE} = 5V		2.4		µs
t_{off}	Turn-off Time			25.0		µs
DC CHARACTERISTICS						
CTR	Current Transfer Ratio, Collector-Emitter	I_F = 5mA, V_{CE} = 5V	50		600	%
$CTR_{(sat)}$		I_F = 8mA, V_{CE} = 0.4V	30			%
$V_{CE(sat)}$	Saturation Voltage	I_F = 8mA, I_C = 2.4mA			0.40	V

Isolation Characteristics

Symbol	Characteristic	Test Conditions	Min.	Typ.*	Max.	Units
V_{ISO}	Input-Output Isolation Voltage	$I_{I-O} \leq$ 10µA, t = 1min.	5000			Vac(rms)
R_{ISO}	Isolation Resistance	V_{I-O} = 500VDC	10^{11}			Ω
C_{ISO}	Isolation Capacitance	f = 1MHz		0.5		pF

*All typicals at T_A = 25°C

Typical Performance Curves

Fig. 1 Normalized CTR vs. Forward Current

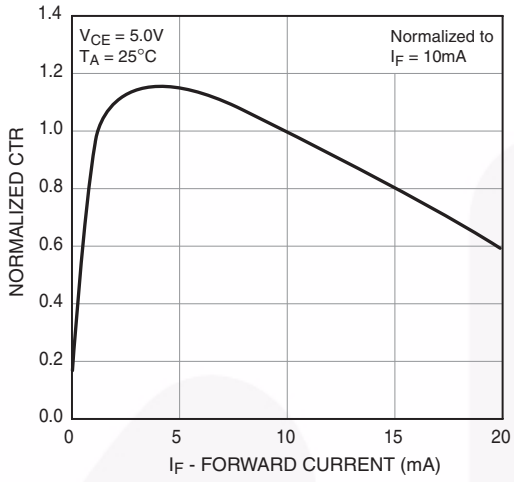


Fig. 2 Normalized CTR vs. Ambient Temperature

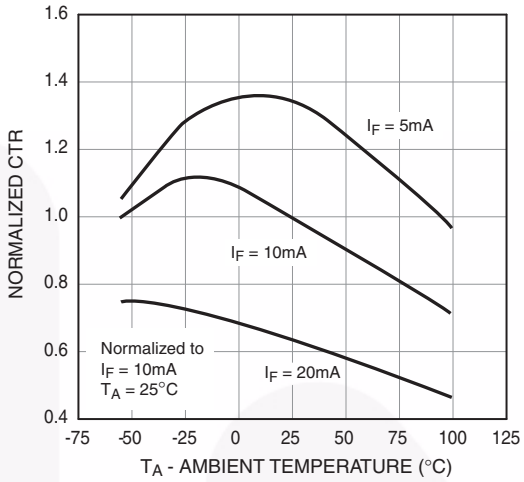


Fig. 3 Dark Current vs. Ambient Temperature

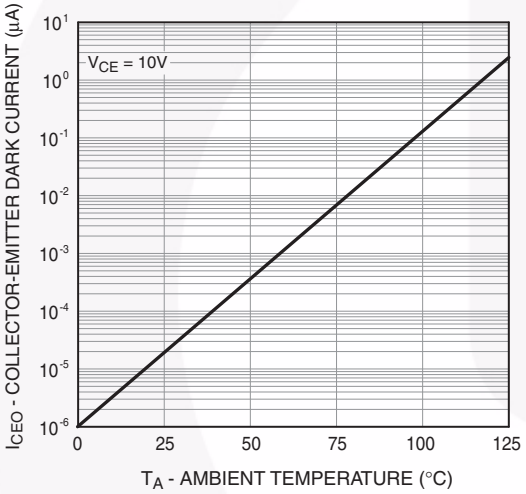


Fig. 4 Switching Speed vs. Load Resistor

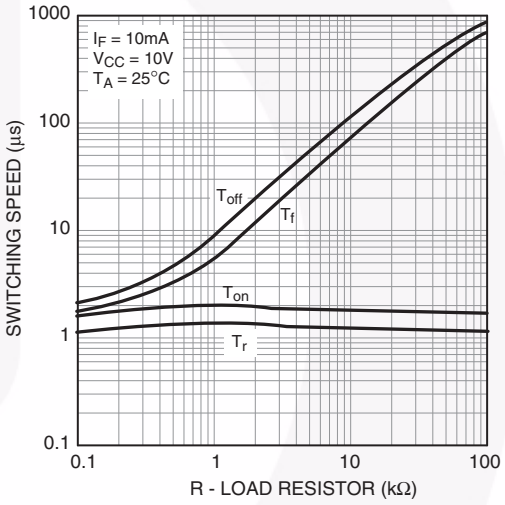


Fig. 5 LED Forward Voltage vs. Forward Current

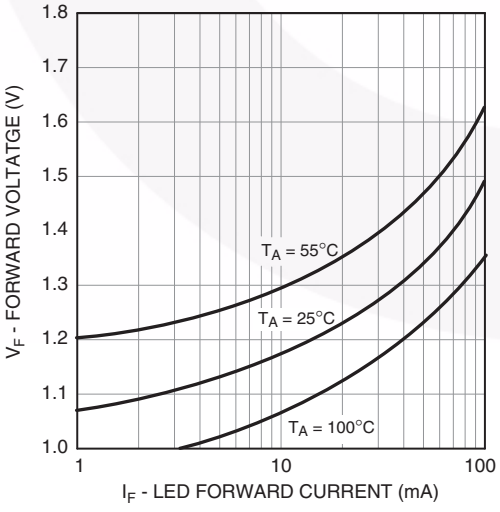
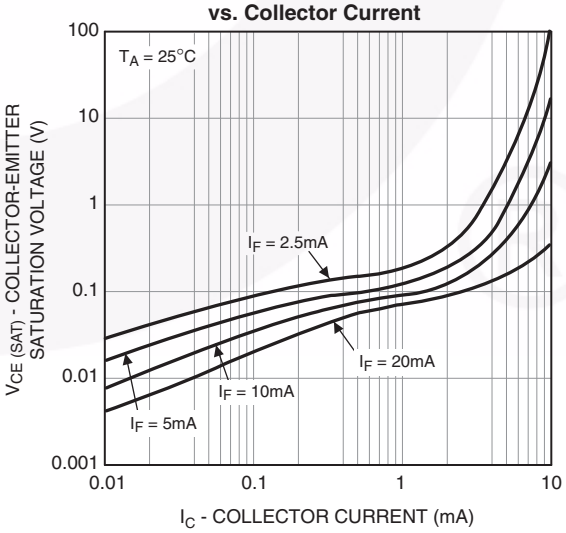
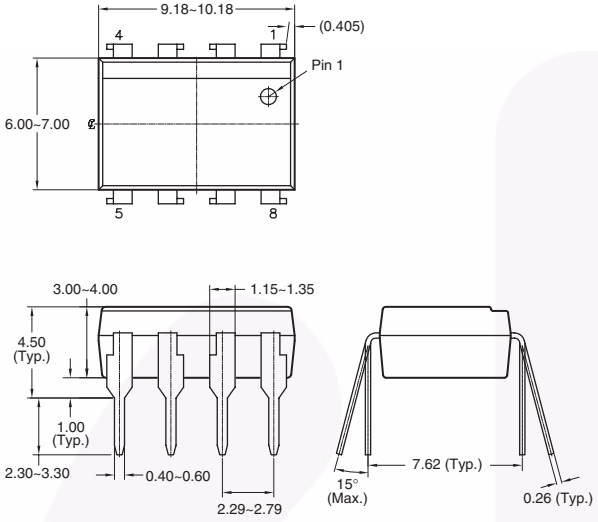


Fig. 6 Collector-Emitter Saturation Voltage vs. Collector Current

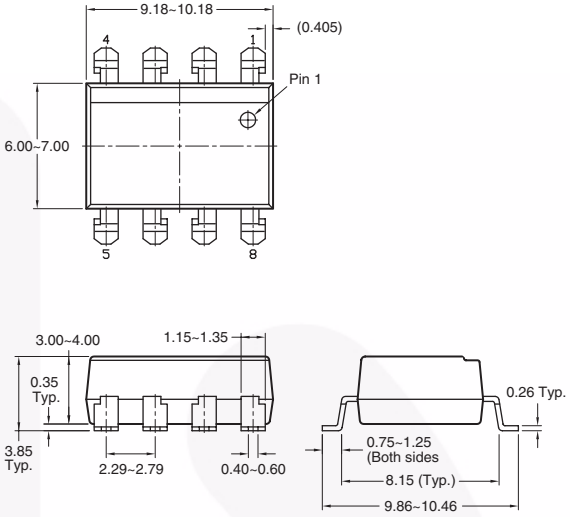


Package Dimensions

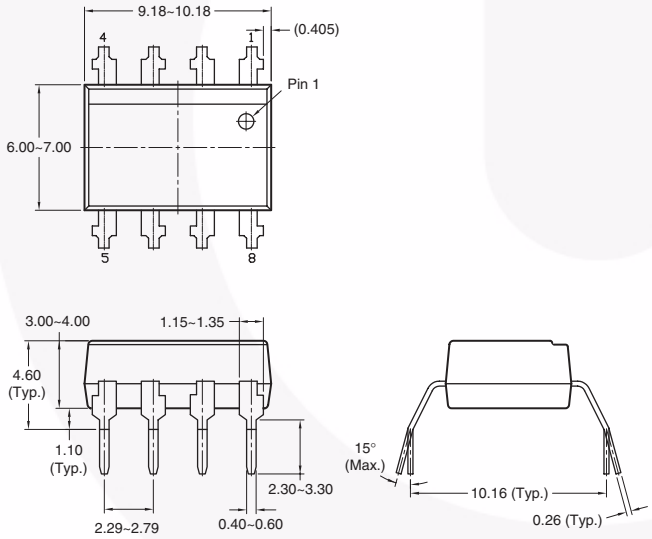
Through Hole



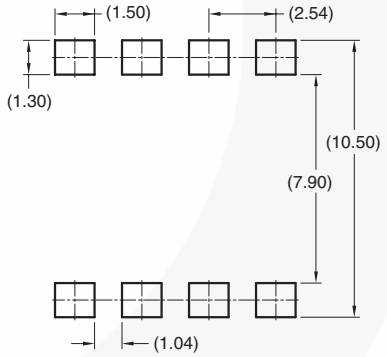
Surface Mount



0.4" Lead Spacing



Recommend Pad Layout for Surface Mount Leadform



Note:
All dimensions are in millimeters.

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

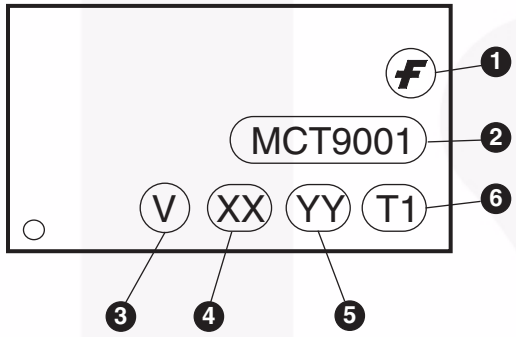
Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings:

http://www.fairchildsemi.com/packaging/

Ordering Information

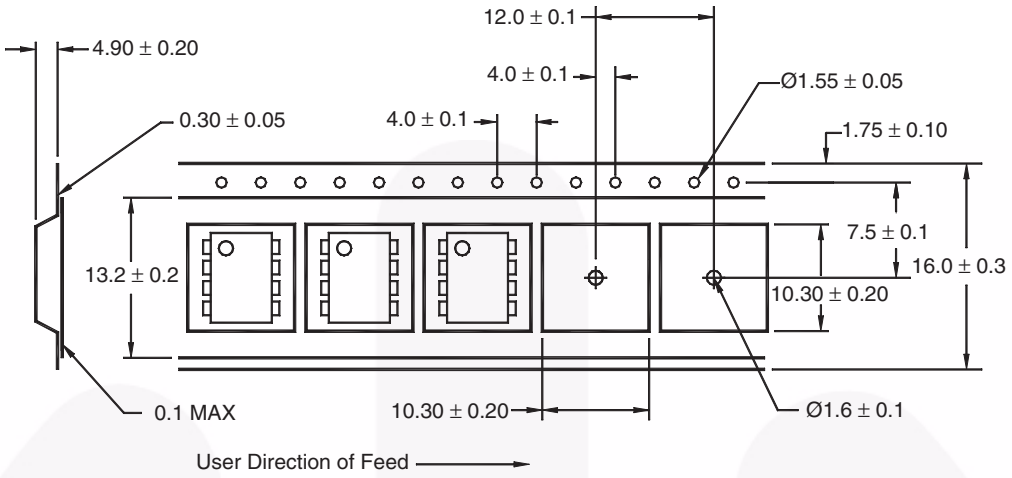
Option	Example Part Number	Description
No Option	MTC9001	Standard Through Hole
S	MTC9001S	Surface Mount Lead Bend
SD	MTC9001SD	Surface Mount; Tape and Reel
W	MTC9001W	0.4" Lead Spacing

Marking Information



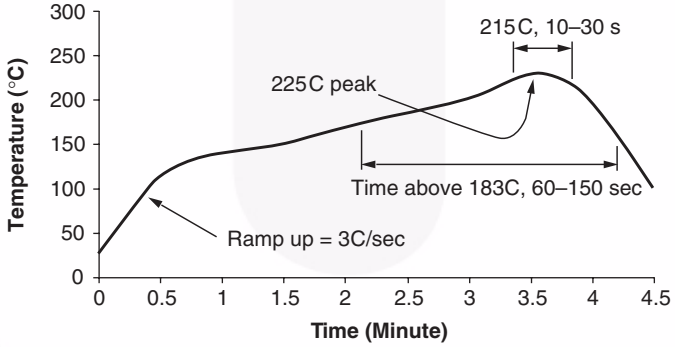
Definitions	
1	Fairchild logo
2	Device number
3	VDE mark (Note: Only appears on parts ordered with VDE option – See order entry table)
4	Two digit year code, e.g., ‘03’
5	Two digit work week ranging from ‘01’ to ‘53’
6	Assembly package code

Carrier Tape Specifications



Note:
All dimensions are in inches (millimeters)

Reflow Profile



- Peak reflow temperature: 225C (package surface temperature)
- Time of temperature higher than 183C for 60–150 seconds
- One time soldering reflow is recommended

FAIRCHILD SEMICONDUCTOR®

TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

Build it Now™
CorePLUS™
CorePOWER™
CROSSVOLT™
CTL™
Current Transfer Logic™
EcoSPARK®
EfficentMax™
EZSWITCH™ *
E²CMOS™
ESBC™
Fairchild®
Fairchild Semiconductor®
FACT Quiet Series™
FACT®
FAST®
FastvCore™
FlashWriter® *
FPS™
F-PFS™
FRFET®
Global Power Resource℠
Green FPS™
Green FPS™ e-Series™
GTO™
IntelliMAX™
ISOPLANAR™
MegaBuck™
MICROCOUPLER™
MicroFET™
MicroPak™
MillerDrive™
MotionMax™
Motion-SPM™
OPTOLOGIC®
OPTOPLANAR®
PDP SPM™
Power-SPM™
PowerTrench®
PowerXS™
Programmable Active Droop™
QFET®
QS™
Quiet Series™
RapidConfigure™
Saving our world, 1mW/W/kW at a time™
SmartMax™
SMART START™
SPM®
STEALTH™
SuperFET™
SuperSOT™-3
SuperSOT™-6
SuperSOT™-8
SupreMOS™
SyncFET™
SYSTEM GENERAL®
The Power Franchise®
the power franchise
TinyBoost™
TinyBuck™
TinyLogic®
TINYOPTO™
TinyPower™
TinyPWM™
TinyWire™
TriFault Detect™
µSerDes™
UHC®
Ultra FRFET™
UniFET™
VCX™
VisualMax™
XS™

* EZSWITCH™ and FlashWriter® are trademarks of System General Corporation, used under license by Fairchild Semiconductor.

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
2. A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.fairchildsemi.com, under Sales Support.

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed applications, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address any warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

Rev. I38